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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Timothy H. Daubenspeck	07/07/2008
Jeffery P. Gambino	07/07/2008
Timothy D. Sullivan	07/02/2008

RECEIVING PARTY DATA

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State/Country:	NEW YORK
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12188235

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NAME OF SUBMITTER: Richard M. Kotulak

Total Attachments: 2

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PATENT

REEL: 021359 FRAME: 0866

<u>ASSIGNMENT</u>

Whereas, we

INVENTOR AND CITY

(1) Timothy H. DAUBENSPECK

County of Chittenden

of Colchester.

and State of Vermont.

and (2) Jeffrey P. GAMBINO

County of Chittenden

of Westford.

and State of Vermont,

and (3) Timothy D. SULLIVAN

County of Chittenden

of Underhill.

and State of Vermont.

have invented certain improvements in COMBINATION VIA AND PAD STRUCTURE FOR IMPROVED SOLDER BUMP ELECTROMIGRATION CHARACTERISTICS

DATES THAT

and executed, respectively, a United States patent application therefore on SIGNED THE (1) July 7 , 2008, (2) July 2, 2008, (3) July 2, 2008

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and in all foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

1

Signed and sealed:

PATENT REEL: 021359 FRAME: 0867

(1) Timothy H. DAUBENSPECK	on July 7, 2008	
Jeffrey P. GAMBINO	on <u>Join 2</u> , 2008	
(3) Tanging D Sallman Timothy D. SULLIVAN	on <u>Jirly Z</u> , 2008	

RECORDED: 08/08/2008